

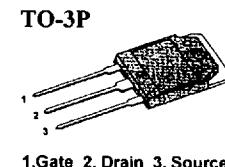
Advanced Power MOSFET

SSH17N60A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ $V_{DS} = 600V$
- Lower $R_{DS(ON)}$: 0.356 Ω (Typ.)

$BV_{DSS} = 600 V$
 $R_{DS(on)} = 0.45 \Omega$
 $I_D = 17 A$



Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	600	V
I_D	Continuous Drain Current ($T_c=25^\circ C$)	17	A
	Continuous Drain Current ($T_c=100^\circ C$)	10.5	
I_{DM}	Drain Current-Pulsed ①	68	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy ②	1103	mJ
I_{AR}	Avalanche Current ①	17	A
E_{AR}	Repetitive Avalanche Energy ①	27.8	mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.0	V/ns
P_D	Total Power Dissipation ($T_c=25^\circ C$)	278	W
	Linear Derating Factor	2.22	W/ $^\circ C$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$
	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	0.45	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink	0.24	--	
$R_{\theta JA}$	Junction-to-Ambient	--	40	

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Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	600	--	--	V	$V_{\text{GS}}=0\text{V}, I_D=250\text{ }\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.72	--	V/ $^\circ\text{C}$	$I_D=250\text{ }\mu\text{A}$ See Fig 7
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{\text{DS}}=5\text{V}, I_D=250\text{ }\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$V_{\text{GS}}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100	nA	$V_{\text{GS}}=-30\text{V}$
I_{DS}	Drain-to-Source Leakage Current	--	--	25	μA	$V_{\text{DS}}=600\text{V}$
		--	--	250	μA	$V_{\text{DS}}=480\text{V}, T_c=125^\circ\text{C}$
$R_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	0.45	Ω	$V_{\text{GS}}=10\text{V}, I_D=8.5\text{A}$ ④
g_{fs}	Forward Transconductance	--	14.41	--	S	$V_{\text{DS}}=50\text{V}, I_D=8.5\text{A}$ ④
C_{iss}	Input Capacitance	--	3050	3960	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	330	380		
C_{rss}	Reverse Transfer Capacitance	--	135	160		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	23	55	ns	$V_{\text{DD}}=300\text{V}, I_D=17\text{A}, R_G=5.3\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	26	60		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	112	235		
t_f	Fall Time	--	36	80		
Q_g	Total Gate Charge	--	128	166	nC	$V_{\text{DS}}=480\text{V}, V_{\text{GS}}=10\text{V}, I_D=17\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	18	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	53.4	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	17	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	68	A	
V_{SD}	Diode Forward Voltage ④	--	--	1.4	V	$T_J=25^\circ\text{C}, I_S=17\text{A}, V_{\text{GS}}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	570	--	ns	$T_J=25^\circ\text{C}, I_F=17\text{A}$
Q_{rr}	Reverse Recovery Charge	--	8.5	--	μC	$dI_F/dt=100\text{A}/\mu\text{s}$ ④

Notes :

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② $L=7\text{mH}, I_{AS}=17\text{A}, V_{DD}=50\text{V}, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$

③ $I_{SD} \leq 17\text{A}, dI/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq \text{BV}_{DSS}$, Starting $T_J=25^\circ\text{C}$

④ Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$

⑤ Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

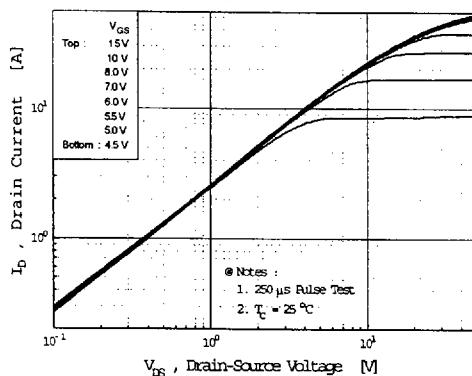


Fig 2. Transfer Characteristics

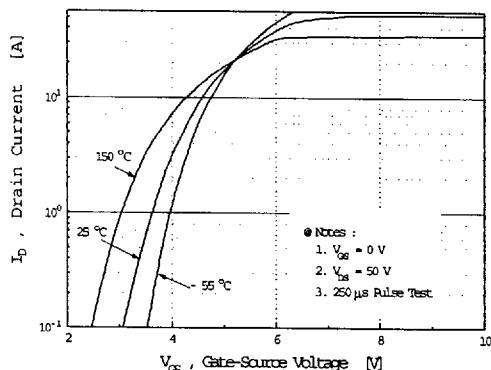


Fig 3. On-Resistance vs. Drain Current

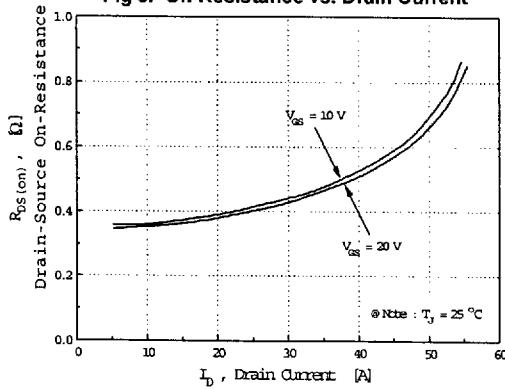


Fig 4. Source-Drain Diode Forward Voltage

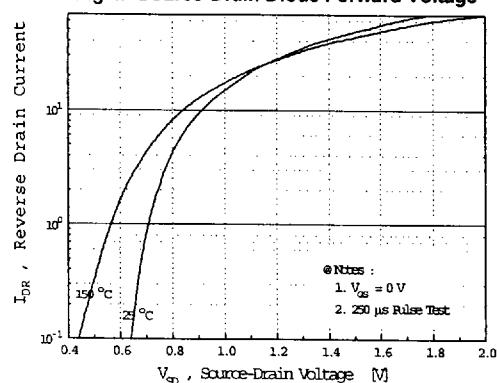


Fig 5. Capacitance vs. Drain-Source Voltage

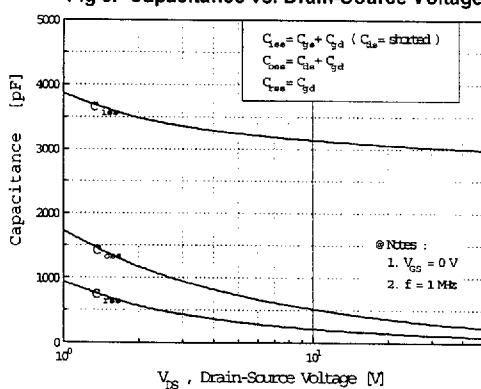
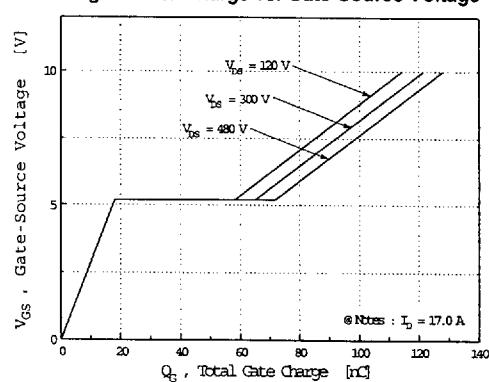
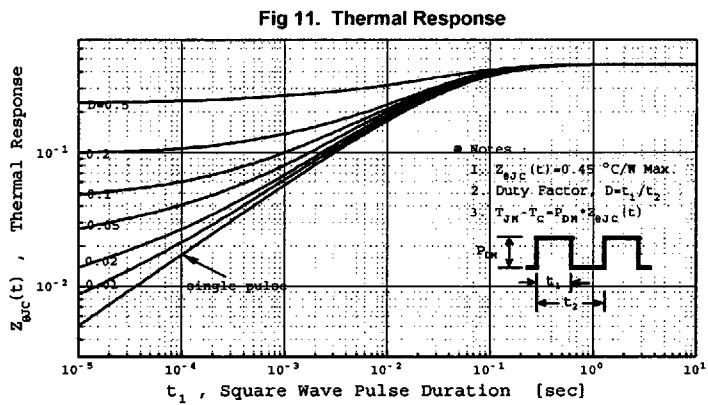
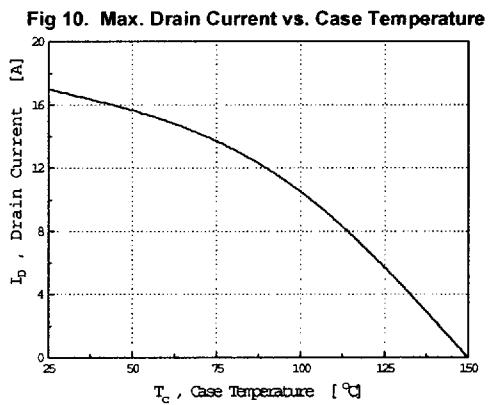
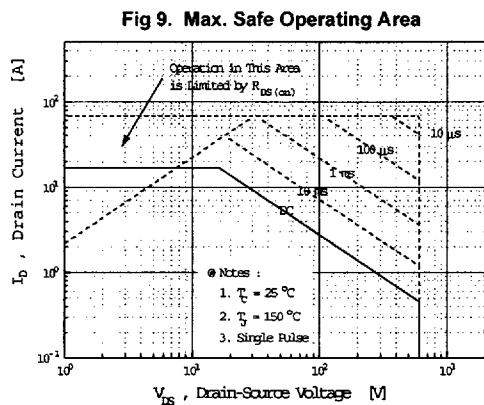
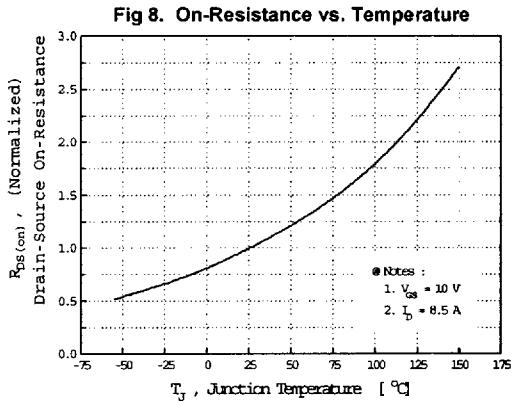
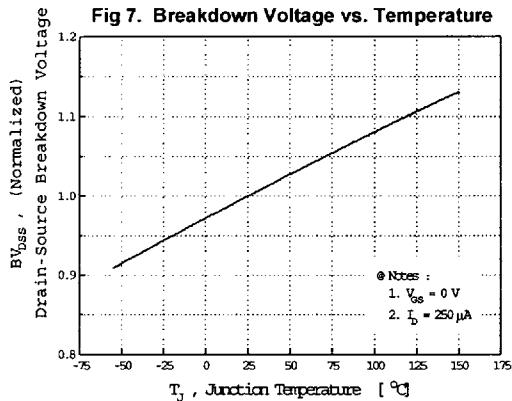


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 12. Gate Charge Test Circuit & Waveform

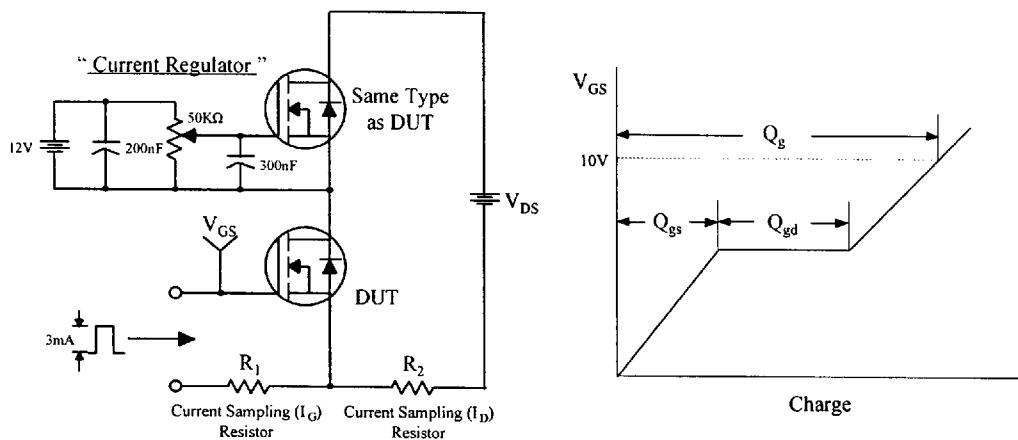


Fig 13. Resistive Switching Test Circuit & Waveforms

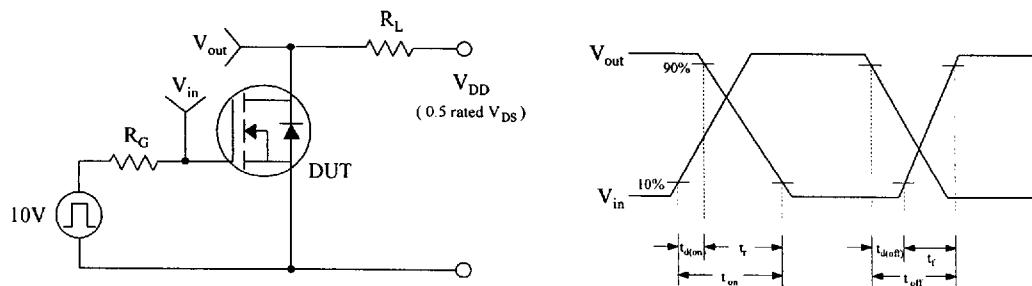
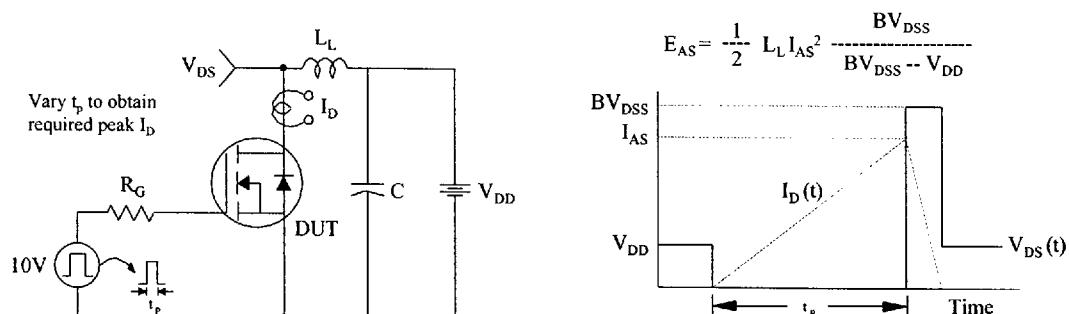


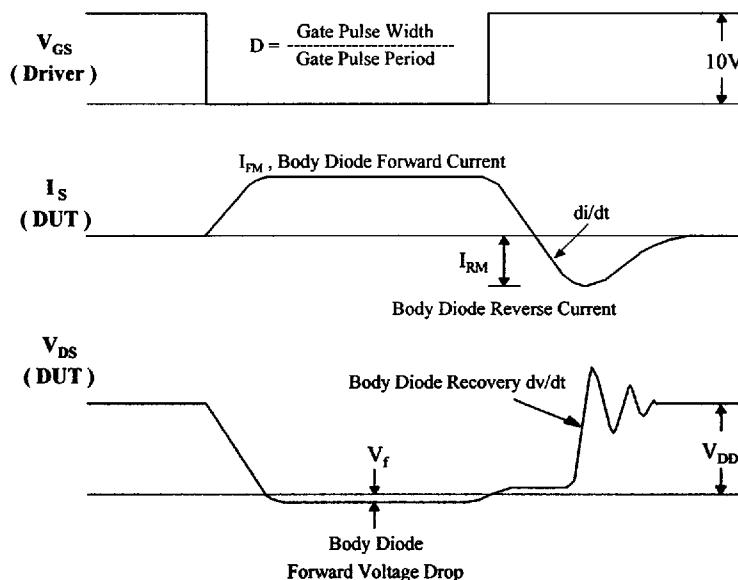
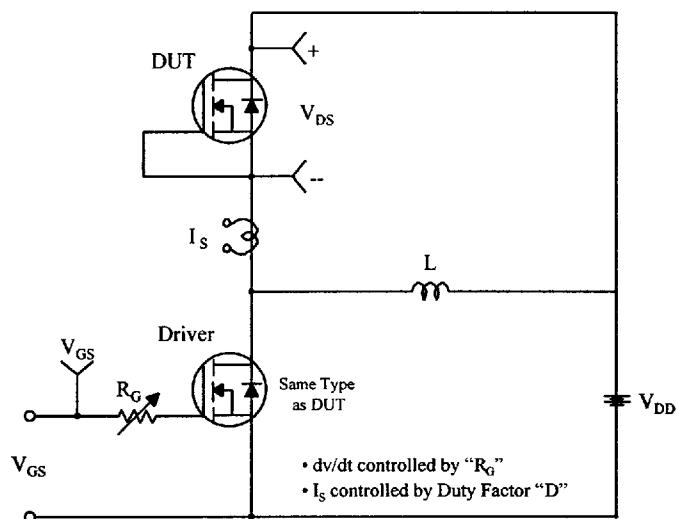
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

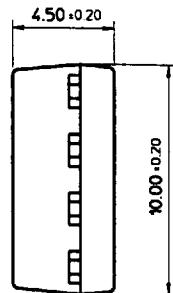
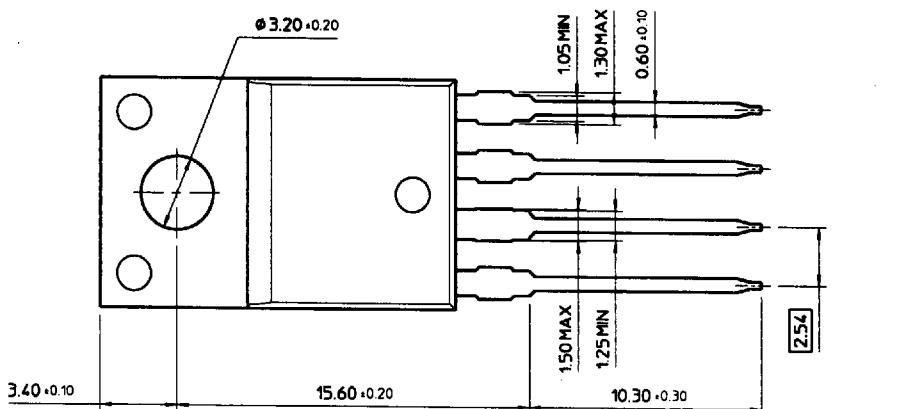


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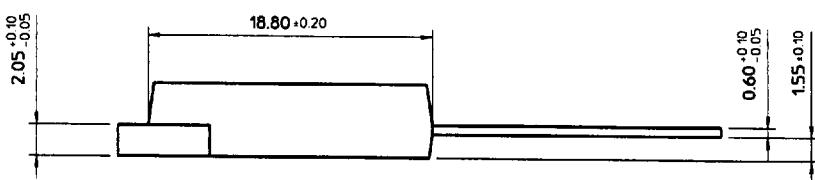
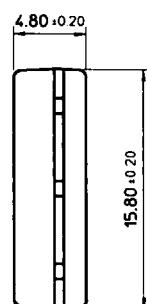
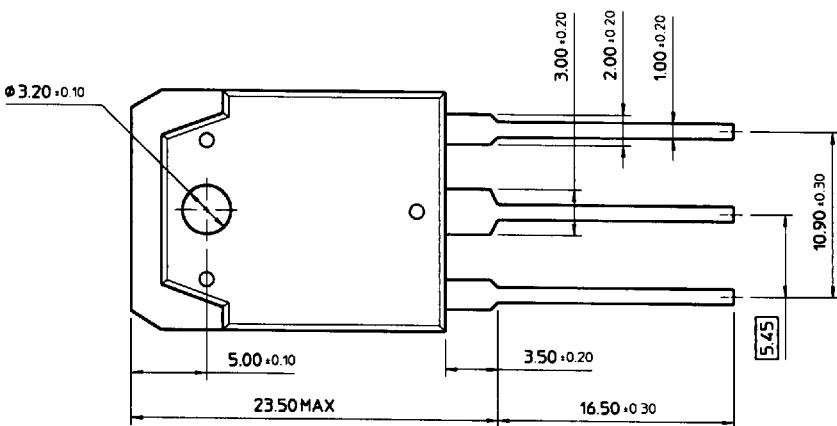
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Dimensions in Millimeters

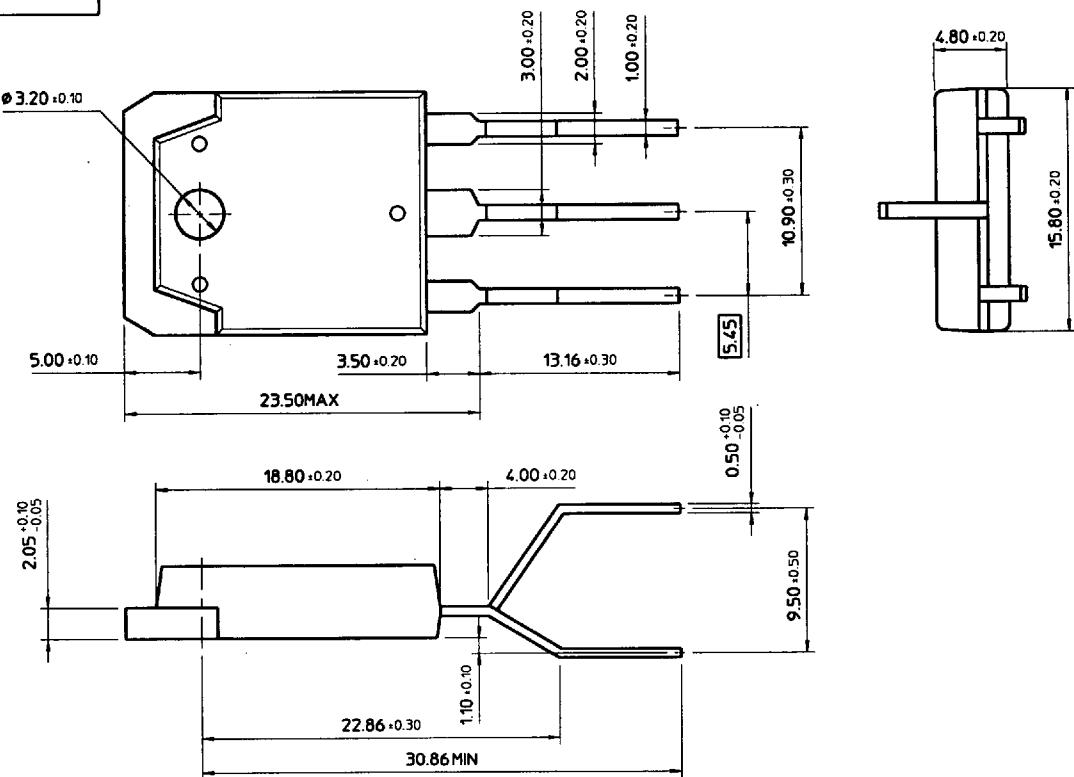
TO-220-F-4L



TO-3P (1)



TO-3P (2)



TO-3PF (1)

